

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	4955	(chip ic chip) and (adhesive tape die adj attach adj (layer film)) same (ppm CTE thermal adj expansion)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/29 16:08
L2	2403	(chip ic chip) and (adhesive tape die adj attach adj (layer film)) with (ppm CTE thermal adj expansion)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/29 16:09
L3	1272	"257"/\$.ccls. and (chip ic chip) and (adhesive tape die adj attach adj (layer film)) with (ppm CTE thermal adj expansion)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/29 16:13
L4	100	"257"/\$.ccls. and (chip ic chip) and (adhesive tape die adj attach adj (layer film)) with ppm with (CTE thermal adj expansion)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/29 16:13
L5	138	(chip ic chip) and (adhesive tape die adj attach adj (layer film)) with ppm with (CTE thermal adj expansion)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/29 16:14

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	4955	(chip ic chip) and (adhesive tape die adj attach adj (layer film)) same (ppm CTE thermal adj expansion)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/29 16:08
L2	2403	(chip ic chip) and (adhesive tape die adj attach adj (layer film)) with (ppm CTE thermal adj expansion)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/29 16:09
L3	1272	"257"/\$.ccls. and (chip ic chip) and (adhesive tape die adj attach adj (layer film)) with (ppm CTE thermal adj expansion)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/29 16:13
L4	100	"257"/\$.ccls. and (chip ic chip) and (adhesive tape die adj attach adj (layer film)) with ppm with (CTE thermal adj expansion)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/29 17:22
L5	138	(chip ic chip) and (adhesive tape die adj attach adj (layer film)) with ppm with (CTE thermal adj expansion)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/29 16:14
L6	11	156/324.4,329,330.ccls. and (chip ic chip) and (adhesive tape die adj attach adj (layer film)) same ppm same(CTE thermal adj expansion)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/29 17:23